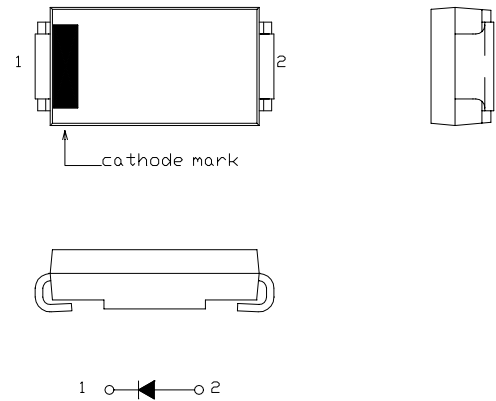


OUTLINE DRAWING

FRD Type : NSU03B60

FEATURES

- * **FLAT-PAK** Surface Mount Device
- * Ultra F_{sat} Recovery
- * Packaged in 16mm Tape and Reel
- * Not Rolling During Assembly
- * For Power Factor Improvement High Frequency Rectification



Maximum Ratings

Approx Net Weight:016g

Rating	Symbol	NSU03B60			Unit
Repetitive Peak Reverse Voltage	V _{RRM}	600			V
Average Rectified Output Current	I _O	0.76	Ta=25 °C *1	50Hz Half Sine	A
		3.0	T1=58 °C *2	Wave Resistive Load	
RMS Forward Current	I _{F(RMS)}	4.71			A
Surge Forward Current	I _{FSM}	35	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T _{jw}	-40 to +150			°C
Storage Temperature Range	T _{stg}	-40 to +150			°C

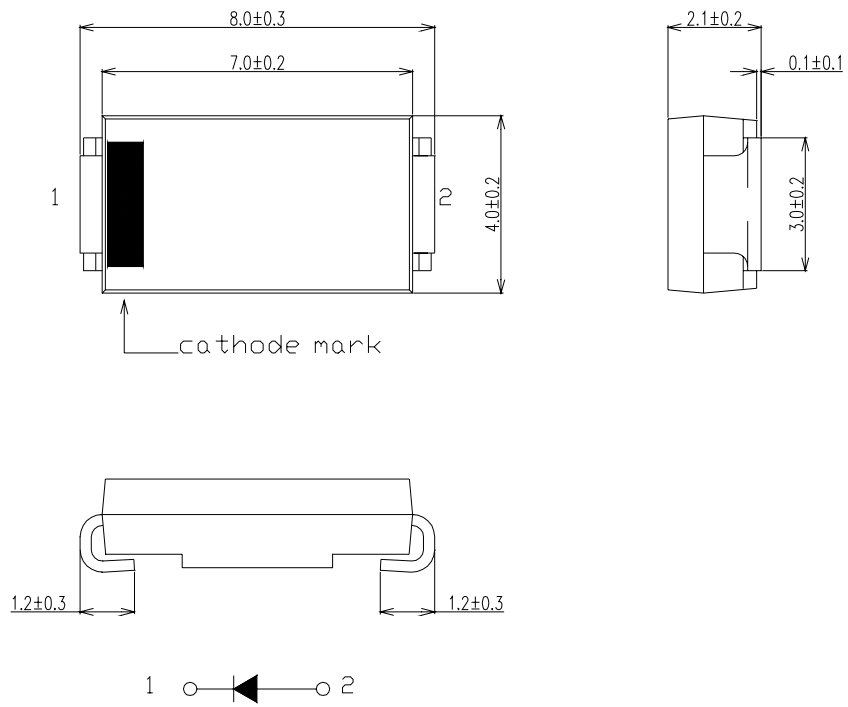
Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	I _{RM}	T _j = 25°C, V _{RM} = V _{RRM}	-	-	20	μA
Peak Forward Voltage	V _{FM}	T _j = 25°C, I _{FM} = 3.0A	-	2.2	2.7	V
Reverse Recovery Time	trr	T _a = 25°C, I _{FM} =3 A -di/dt=50A/μs	-	17	27	ns
Thermal Resistance	R _{th(j-a)}	Junction to Ambient *1	-	-	89	°C /W
	R _{th(j-l)}	Junction to Lead	-	-	13	

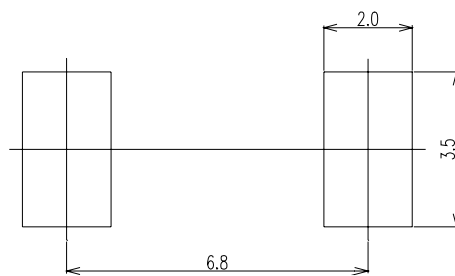
*1 Alumina Substrate Mounted (Soldering Lands=2x3.5mm,Both Sides)

*2 T_l= Lead Temperature

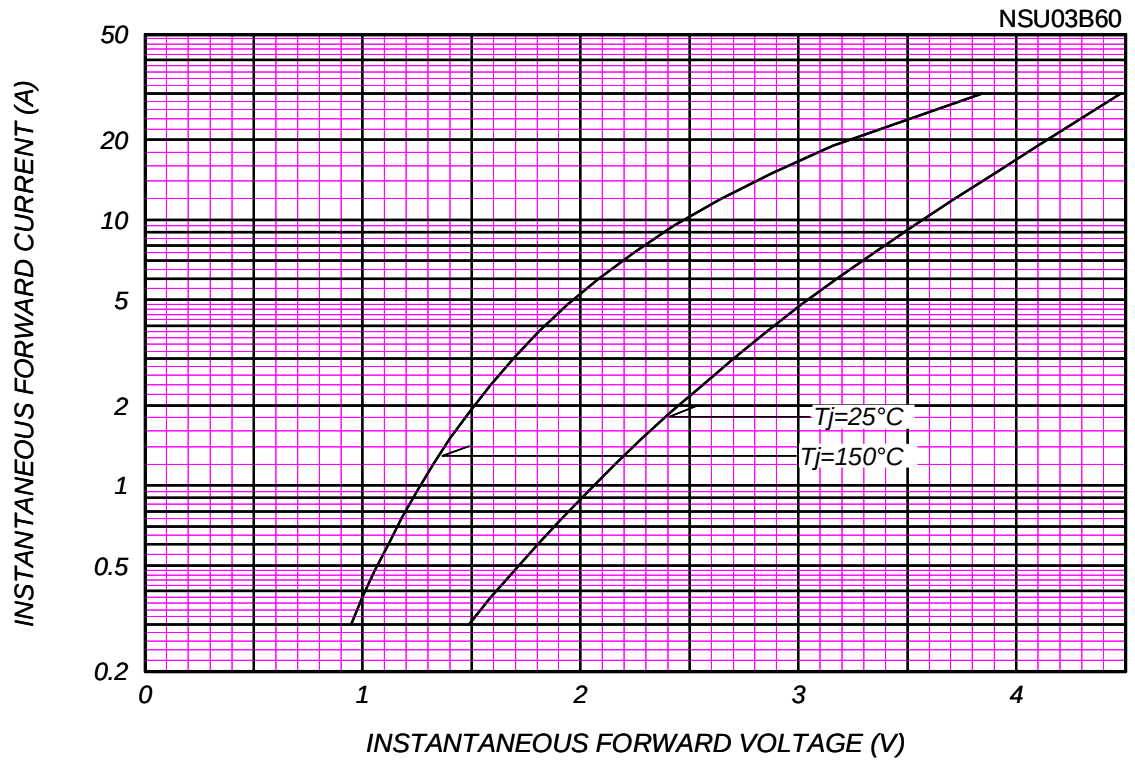
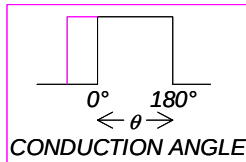
NSU03B60 OUTLINE DRAWING (Dimensions in mm)



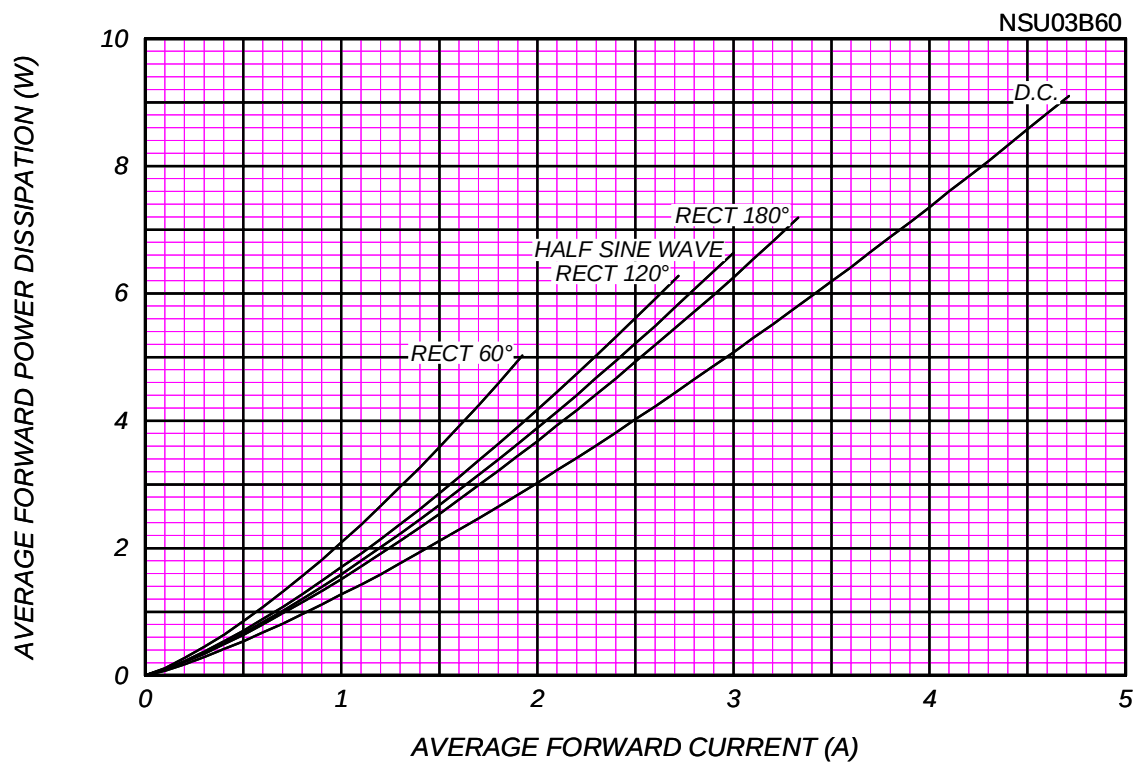
SOLDERING PAD

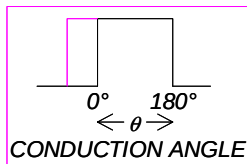


FORWARD CURRENT VS. VOLTAGE



AVERAGE FORWARD POWER DISSIPATION

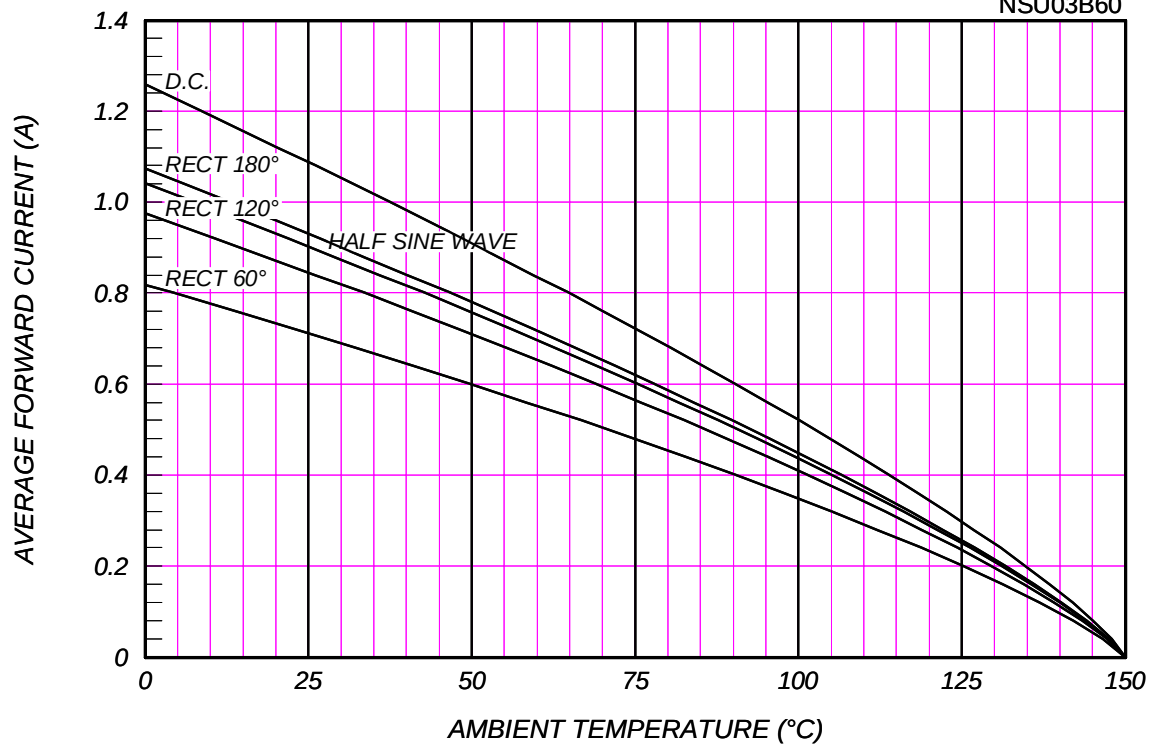
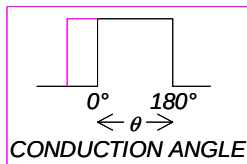




AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

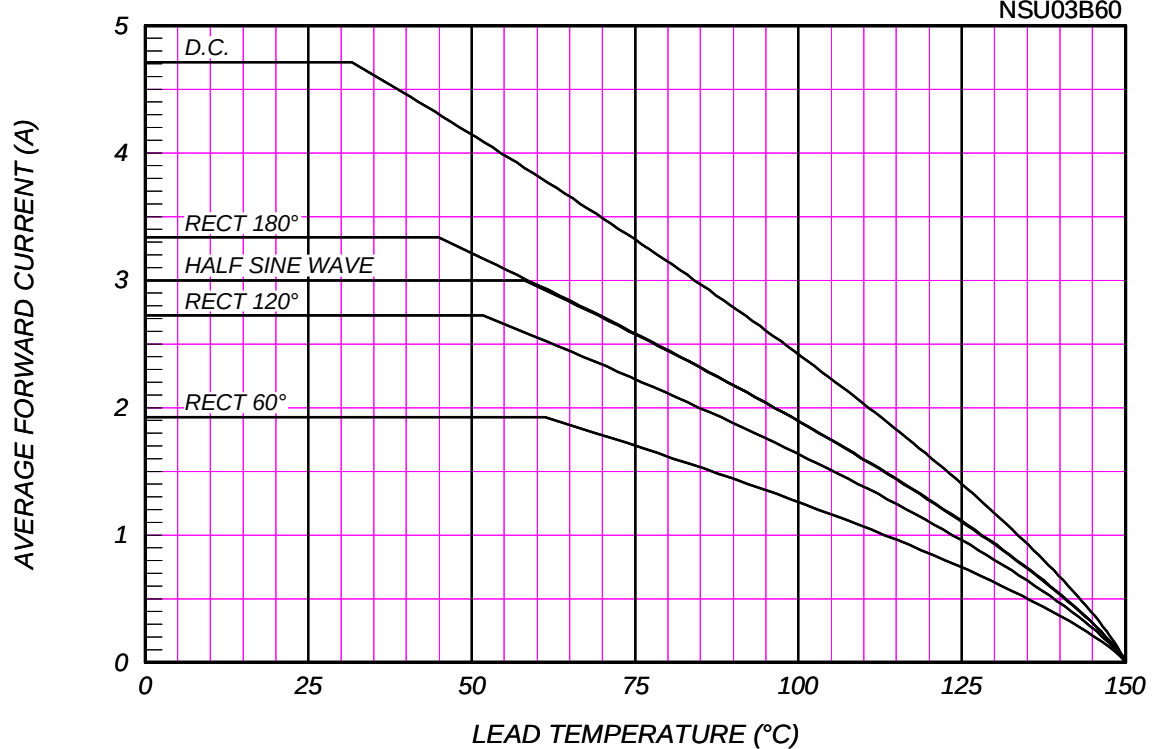
Alumina Substrate Mounted (Soldering Land=2×3.5mm)

NSU03B60



AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

NSU03B60



SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, No Load

NSU03B60

